

IN THE CLAIMS:

The text of all pending claims, (including withdrawn claims) is set forth below. Cancelled and not entered claims are indicated with claim number and status only. The claims as listed below show added text with underlining and deleted text with ~~striketrough~~. The status of each claim is indicated with one of (original), (currently amended), (cancelled), (withdrawn), (new), (previously presented), or (not entered).

Please AMEND claims 10, 12 15 and 17 and add claim 19, in accordance with the following:

Listing of the Claims

1-9. (cancelled)

10. (currently amended) ~~A~~The mold releasing film for printed circuit board production, which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer~~according to claim 17~~, wherein the elastomer (F) is (G) a partially hydrogenated polymer of a block copolymer of an aromatic vinyl compound and a conjugated diene compound.

11. (original) The mold releasing film for printed circuit board production according to claim 10, wherein the content of a bonded aromatic vinyl compound in component (G) is from 5 wt% to 65 wt%.

12. (currently amended) ~~A~~The mold releasing film for printed circuit board production~~according to claim 17~~, which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer, wherein the elastomer (F) is (H) a copolymer of ethylene and a vinyl ester compound.

13. (previously presented) The mold releasing film for printed circuit board production according to claim 17, obtained by molding through an extrusion tubular method.

14. (previously presented) The mold releasing film for printed circuit board production according to claim 17, obtained by molding through a T-die extrusion method.

15. **(currently amended)** ~~A~~The mold releasing film for printed circuit board production ~~according to claim 17, which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer, the mold releasing film~~ having a contact angle between the film surface of its outermost surface layer and a water drop of 80° or more.

16. **(previously presented)** The mold releasing film for printed circuit board production according to claim 17, wherein the printed circuit board is a flexible printed circuit board.

17. **(currently amended)** A mold releasing film for printed circuit board production, which has a multilayer structure comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more and a layer (Q) containing (F) an elastomer, wherein the layer (Q) does not contain polyphenylene ether.

18. **(previously presented)** A method for producing a printed circuit board comprising hot-pressing a copper-clad laminate or a copper foil and a prepreg or a heat-resistant film along with a mold-releasing film,
wherein the mold releasing film is a film comprising a resin layer (P) containing (A) a polyphenylene ether-based resin in an amount of 50 wt% or more.

19. **(new)** The mold releasing film for printed circuit board production according to claim 17, wherein the mold releasing film has a thickness of from 50 to 300 μm.

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